CLAIMS:

What is claimed is:

1. An active thermal interposer (ATI) device for use in testing a device under test (DUT), said ATI device comprising:

a body layer having a first surface and a second surface, wherein said first surface is operable to be disposed adjacent to a cold plate of a thermal head and wherein said second surface is operable to be disposed adjacent to said DUT during testing thereof;

a plurality of heater elements disposed within said body layer;

a plurality of recessed pads disposed within recesses of said first surface of said body layer and wherein said plurality of recessed pads are electrically coupled to said plurality of heater elements; and

a plurality of copper discs disposed on top of, and in electrical contact with, said plurality of recessed pads within said recesses and aligned wherein said plurality of cooper discs remain recessed with respect to said first surface and wherein said plurality of copper discs is operable to contact a corresponding plurality of pins of said thermal head to receive driving electrical signals therefrom.

2. The ATI device of Claim 1 wherein:

said plurality of heater elements comprise tungsten traces;

said plurality of recessed pads are gold;

said plurality of pins comprise pogo pins;

said plurality of copper discs functions to spread out heat and current with respect to said plurality of recessed pads; and

said body layer comprises ceramic material.

3. The ATI device of Claim 1 wherein two or more copper discs of said plurality of copper discs are disposed on top of, and in electrical contact with, each recessed pad of said plurality of recessed pads and wherein said recesses are oval in shape.

4. The ATI device of Claim 1 wherein one copper disc of said plurality of copper discs is disposed on top of, and in electrical contact with, each recessed pad of said plurality of recessed pads and wherein said recesses are circular in shape.

5. The ATI device of Claim 1 wherein said plurality of copper discs are affixed to said plurality of recessed pads.

6. The ATI device of Claim 1 wherein said plurality of copper discs are soldered to said plurality of recessed pads.

7. The ATI device of Claim 1 wherein said plurality of recessed pads are electrically coupled to said plurality of heater elements using a plurality of via connections and wherein said plurality of via connections comprise tungsten vias.

8. The ATI device of Claim 1 wherein said heater elements comprise high temperature co-fired ceramic (HTCC).